

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1016cn8#pbf

(Engineering Calculation)

PDIP

(printed on: 2020-07-11 19:59:05)

TOTAL MASS (g) : 0.498048

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001488 | 1000000 | 2987.66235352 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.149760 | 975000 | 300693.71875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003686 | 24000 | 7400.88916016 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000046 | 300 | 92.3605270386 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000108 | 700 | 216.846450806 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.153600 | 1000000 | 308403.84375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.012410 | 1000000 | 24917.8457031 | | |
| | | External Plating Total: | | | | 0.012410 | 1000000 | 24917.8457031 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001228 | 1000000 | 2465.62451172 | | |
| Internal Plating Total: | | | | 0.001228 | 1000000 | 2465.62451172 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000565 | 750000 | 1134.42822266 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000188 | 250000 | 377.473449707 | | |
| Die Attach Total: | | | | 0.000753 | 1000000 | 1511.90161133 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.044334 | 135000 | 89015.46875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.282424 | 860000 | 567061.5 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001642 | 5000 | 3296.86938477 | | |
| | | Encapsulation Total: | | | | 0.328400 | 1000000 | 659373.8125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000169 | 1000000 | 339.324554443 | | |
| | | | | | TOTAL MASS (g) : | 0.498048 | | |